

JP 5-271389

AN 1994:193300 CAPLUS
 DN 120:193300
 TI Flexible epoxy resin compositions and their uses as sealing materials or adhesives
 IN Yonezawa, Akira; Kawai, Atsushi
 PA Tairu Mento Kk, Japan
 SO Jpn. Kokai Tokkyo Koho, 14 pp.
 CODEN: JKXXAF
 DT Patent
 LA Japanese
 IC ICM C08G059-40
 ICS C08G059-50; C08L063-00; C08L083-06; C09J163-00; C09K003-10
 CC 37-6 (Plastics Manufacture and Processing)
 Section cross-reference(s): 38, 42

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
✓ PI	JP 05271389	A2	19931019	JP 1992-98864	19920325
AB	Storage-stable title compns. comprise epoxy resins, modified silicone resins, catalysts for the silicone resins, dehydration agents, and di- and/or triketimines from polyoxyalkylenediamine and polyoxyalkylenetriamines. A compn. contg. EP-4100 100, poly(methyldimethoxysilyl ether) (MSP20A) 50, Bu2Sn oxide in DOP 0.5, vinyltrimethoxysilane (KBM 1003) 0.5, CaCO3 207, TiO2 23, ketimine of polyoxypropylenetriamine and MIBK 80 parts was stable under N at 50.degree. for 7 days, and gave cured test pieces with elongation 200% and tensile strength 50 kgf/cm2.				
ST	flexible epoxy resin sealant adhesive; ketimine polyoxyalkylenediamine flexible epoxy resin; silicone resin flexible epoxy resin				
IT	Adhesives Sealing compositions (epoxy resin compns., contg. ketimines of polyoxypropylenediamine and triamine, flexible and storage-stable)				
IT	Siloxanes and Silicones, uses RL: USES (Uses) (di-Me, ethoxy-terminated, epoxy resins, flexible and storage-stable, for adhesive and sealant)				
IT	11121-15-6, EP 4000 25085-99-8, EP 4100 RL: USES (Uses) (compns., contg. ketimines of polyoxypropylenediamine and triamine, flexible and storage-stable, for adhesive and sealant)				
IT	108-10-1D, MIBK, ketimines with polyoxypropylenetriamine 2768-02-7, Vinyltrimethoxysilane 9003-11-6D, Ethylene oxide-propylene oxide copolymer, diamine derivs., ketimine with MIBK 25322-69-4D, Polyoxypropylene, triamine derivs., ketimine with MIBK 120041-50-1 RL: USES (Uses) (epoxy resin compns. contg., flexible and storage-stable, for adhesive and sealant)				
IT	77396-40-8 RL: USES (Uses) (epoxy resins, flexible and storage-stable, for adhesive and sealant)				

WEST**End of Result Set**

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L4: Entry 1 of 1

File: DWPI

Oct 19, 1993

DERWENT-ACC-NO: 1993-365304

DERWENT-WEEK: 199346

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TITLE: One-pack flexible epoxy! resin compsn. for sealing cpds. and adhesives - contains epoxy! resin, ketimine, modified silicone resin and its catalyst and a dehydrant, is storage stable, easily cured and has good flexibility

PATENT-ASSIGNEE:

ASSIGNEE

TAIRU MENTO KK

CODE

TAIRN

PRIORITY-DATA:

1992JP-0098864

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PATENT-FAMILY:

PUB-NO

PUB-DATE

LANGUAGE

PAGES

MAIN-IPC

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APPLICATION-DATA:

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APPL-DESCRIPTOR

APPL-NO

APPL-NO

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N/A

INT-CL (IPC): C08G 59/40; C08G 59/50; C08L 63/00; C08L 83/06; C09J 163/00; C09K 3/10

ABSTRACTED-PUB-NO: JP05271389A

BASIC-ABSTRACT:

Compsn. contains (a) an epoxy resin; (b) a ketimine; (c) a modified silicone resin; (d) a catalyst for the modified silicone resin and (e) a dehydrant. The ketimine is a cpd. of formula (I), where A is residue of 9 or higher C polyoxyalkylenediamine, and R1-4 are H, 1-6C alkyl or phenyl.

The wt. ratio of modified silicone resin to epoxy resin is pref. 100:1-1000.

USE/ADVANTAGE - The compsn. have storage stability and cure at ordinary temp. to give cured compsn. with good flexibility. The epoxy resin compsn. are useful for sealing cpds. and as adhesives for concrete, glass, wood and metals. The ketimine used as a curative, does not react with epoxy resin in absence of water and the storage stability and flexibility of the cured compsn. are improved.

In an example, a mixt. of 100 pts.wt. 'EP-4100' (RTM), an epi-bis epoxy resin, 50 pts.wt. poly(methyldimethoxysilyl ether), 207 pts.wt. CaCO₃ and 23 pts.wt. titanium oxide was stirred under 20 Torr 80 pts.wt. of a ketimine obtd. by dehydration of polyoxypropylenediamine with a mol.wt. of 400 and methyl isobutyl ketone. 0.5 pts.wt. vinyltrimeth oxysilane (dehydrant) and 0.5 pts.wt. dibutyltin oxide dioctyl phthalate soln. (catalyst) were added to the mixt. and the new mixt. was stirred under reduced pressure to give an epoxy resin compsn. with a tensile strength of 50 kgf/cm², an elongation of 200% and an adhesion strength or mortar break.

RN 11121-15-6 REGISTRY
 CN Poly[oxy(methyl-1,2-ethanediyl)],
 .alpha.,.alpha.'-[(1-methylethylidene)di-
 4,1-phenylene]bis[.omega.-(oxiranylmethoxy)-, homopolymer (9CI) (CA

INDEX

NAME)

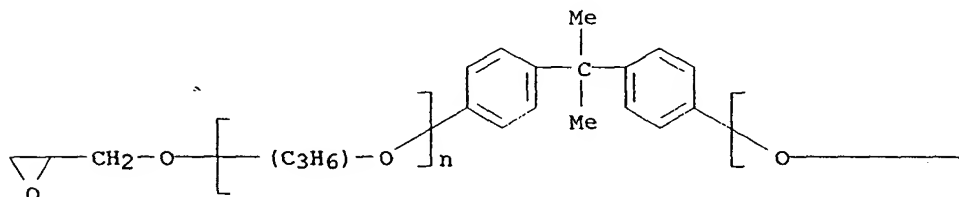
OTHER NAMES:

CN Adeka EP 4000
 CN Adeka Resin EP 4000
 CN ADK 4000
 CN EP 4000
 CN Epiclon 717
 CN Gurishieru BPP 350
 CN Rikaresin BPO 20E
 DR 54667-37-7, 60267-15-4, 63278-42-2, 39354-76-2
 MF ((C3 H6 O)n (C3 H6 O)n C21 H24 O4)x
 CI PMS, COM
 PCT Epoxy resin, Polyether
 LC STN Files: CA, CAPLUS, CHEMLIST, IFICDB, IFIPAT, IFIUDB, USPATFULL

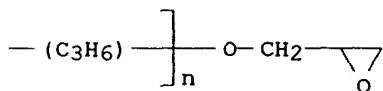
CM 1

CRN 55236-42-5
 CMF (C3 H6 O)n (C3 H6 O)n C21 H24 O4
 CCI IDS, PMS

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93 REFERENCES IN FILE CA (1967 TO DATE)
 23 REFERENCES TO NON-SPECIFIC DERIVATIVES IN FILE CA
 93 REFERENCES IN FILE CAPLUS (1967 TO DATE)